

Symbol

V_{DSS}

V_{DGR}

V_{GSS}

 \mathbf{V}_{GSM}

I_{D25}

I_{DM} \mathbf{I}_{AR}

 $\acute{\mathbf{E}}_{\mathrm{AR}}$

dv/dt

 $\boldsymbol{P}_{_{\boldsymbol{D}}}$

 T_{j}

 $\mathbf{T}_{\underline{\mathsf{stg}}}$

T,

M

T_{SOLD}

Weight

PolarHV[™] HiPerFET **Power MOSFET**

N-Channel Enhancement Mode Avalanche Rated Fast Intrinsic Diode

Test Conditions

Continuous

Transient

 $T_c = 25^{\circ} C$

 $T_{c} = 25^{\circ} C$

 $T_{\rm C}^{\circ} = 25^{\circ} \rm C$

 $T_{c} = 25^{\circ} C$

 $T_{c} = 25^{\circ} C$

TO-268

 $T_{J} \leq 150^{\circ} C$, $R_{G} = 5 \Omega$

Plastic body for 10 s

PLUS220, PLUS220SMD

 $T_{1} = 25^{\circ} \text{ C to } 150^{\circ} \text{ C}$

 $T_{\perp} = 25^{\circ} \text{ C to } 150^{\circ} \text{ C}; R_{GS} = 1 \text{ M}\Omega$

 $T_{\rm C} = 25^{\circ}$ C, pulse width limited by $T_{\rm IM}$

 $I_{_{S}} \le I_{_{DM}}$, di/dt ≤ 100 A/ μ s, $V_{_{DD}} \le V_{_{DSS}}$,

1.6 mm (0.062 in.) from case for 10 s

Mounting torque (TO-247, TO-3P)

Mounting force (PLUS220, PLUS220SMD)

IXFH 30N50P IXFT 30N50P IXFV 30N50P IXFV 30N50PS

500 $V_{\rm DSS}$ 30 Α D25 ≤ $\mathbf{R}_{\mathrm{DS(on)}}$ 200 $m\Omega$ 200 ns



500

500

±30

±40

30

75

30

40

1.2

10

460

150

300

260

11 65/2.5 15 N/lb.

5

1.13/10

-55 ... +150

-55 ... +150



٧

٧

٧

Α

Α

Α

J

mJ

V/ns

W

°С °С

 $^{\circ}C$

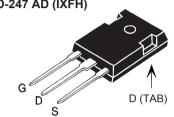
٥С

°C

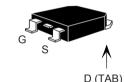
g

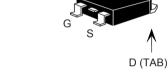
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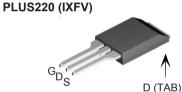
Nm/lb.in



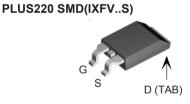
TO-268 (IXFT)







$G_{D_{S}}$	D (TA



G = Gate	D = Drain
S = Source	TAB = Drain

	10-247			0	<u> 9</u>
Symbol	Test Conditions $(T_J = 25^{\circ} C, \text{ unless otherwise specified})$	Ch Min.	aracter Typ.	istic Va	alues
BV _{DSS}	V_{GS} = 0 V, I_{D} = 250 μ A	500			V
$V_{\rm GS(th)}$	$V_{DS} = V_{GS}$, $I_{D} = 4 \text{ mA}$	3.0		5.0	V
I _{GSS}	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA
I _{DSS}	$V_{DS} = V_{DSS}$ $V_{GS} = 0 \text{ V}$ $T_{J} = 125^{\circ}\text{ C}$			25 750	μ Α μ Α
R _{DS(on)}	V_{GS} = 10 V, I_{D} = 0.5 I_{D25} Pulse test, t ≤300 μ s, duty cycle d ≤ 2 %		165	200	mΩ

- International standard packages
- Unclamped Inductive Switching (UIS)
- Low package inductance
- easy to drive and to protect

Advantages

- Easy to mount
- Space savings
- High power density



Symbol		Test Conditions		Characteristic Values		
		(T _J = 25° C	C, unles: Min.	s otherw Typ.	rise specified) Max.	
g _{fs}		V_{DS} = 20 V; I_{D} = 0.5 I_{D25} , pulse test	17	27	S	
C _{iss})			4150	pF	
\mathbf{C}_{oss}	}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		445	pF	
\mathbf{C}_{rss}	J			28	pF	
t _{d(on)})			25	ns	
t,		$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 V_{DSS}, I_{D} = 0.5 I_{D25}$		24	ns	
$\mathbf{t}_{d(off)}$		$R_{_{G}} = 5 \Omega (External)$		82	ns	
t _f)			24	ns	
$\mathbf{Q}_{\mathrm{g(on)}}$)			70	nC	
\mathbf{Q}_{gs}	}	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \text{ V}_{DSS}, I_{D} = 0.5 \text{ I}_{D25}$		27	nC	
\mathbf{Q}_{gd}				22	nC	
R _{thJC}					0.27° C/W	
R_{thCs}		(TO-247, PLUS220)		0.21	°C/W	

Source-Drain Diode

Characteristic Values

(T₁ = 25° C, unless otherwise specified)

Symbol	Test Conditions	Min.	Тур.	Max.	
I _s	$V_{GS} = 0 V$			30	Α
I _{SM}	Repetitive			90	Α
$\mathbf{V}_{\mathtt{SD}}$	$I_{_F} = I_{_S}, V_{_{\mathrm{GS}}} = 0 \text{V},$ Pulse test, t \leq 300 µs, duty cycle d \leq 2 %			1.5	V
t _{rr}	I _F = 25 A; -di/dt = 100 A/μs			200	ns
I _{RM}	$V_{R} = 100 \text{ V}; V_{GS} = 0 \text{ V}$		6		Α
\mathbf{Q}_{RM}			0.6		μС

Characteristic Curves

Fig. 1. Output Characteristics

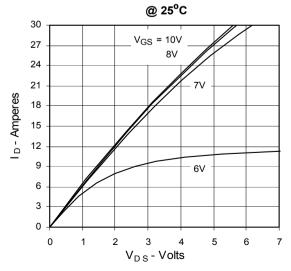
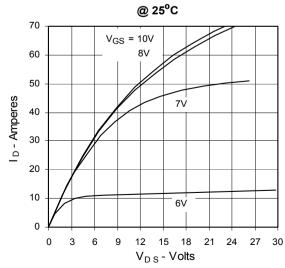


Fig. 2. Extended Output Characteristics



IXYS reserves the right to change limits, test conditions, and dimensions.



IXFH 30N50P IXFT 30N50P IXFV 30N50PS

Fig. 3. Output Characteristics

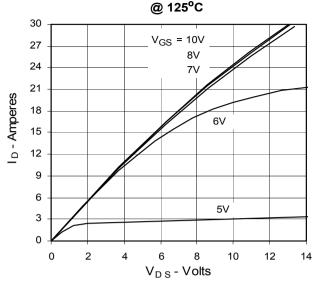


Fig. 4. $R_{DS(on)}$ Normalized to 0.5 I_{D25} Value vs. Junction Temperature

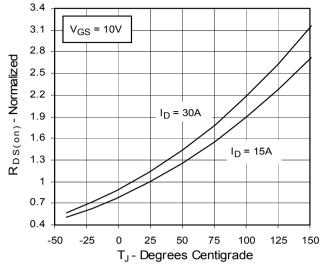


Fig. 5. $R_{DS(on)}$ Normalized to 0.5 I_{D25} Value vs. I_D

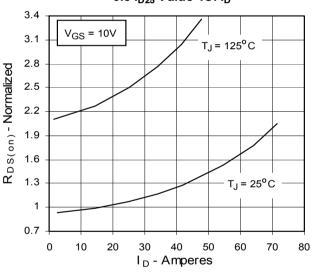


Fig. 6. Drain Current vs. Case Temperature

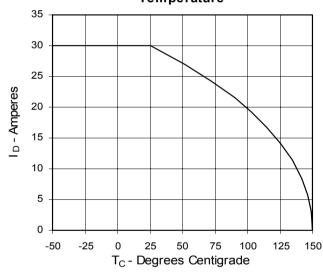


Fig. 7. Input Admittance

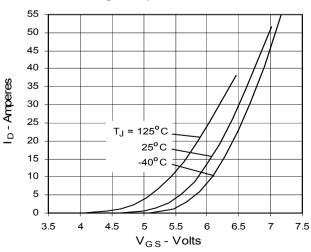


Fig. 8. Transconductance

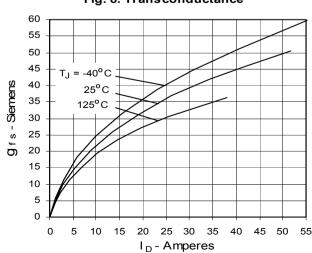




Fig. 9. Source Current vs. Source-To-Drain Voltage

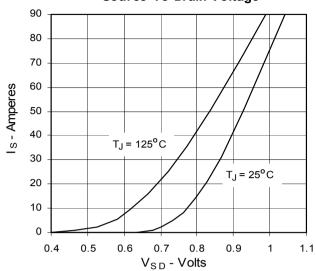


Fig. 10. Gate Charge

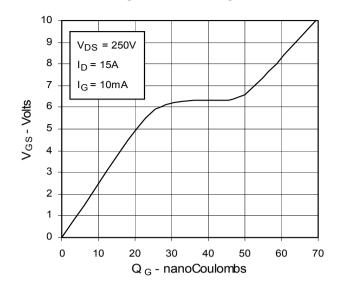


Fig. 11. Capacitance

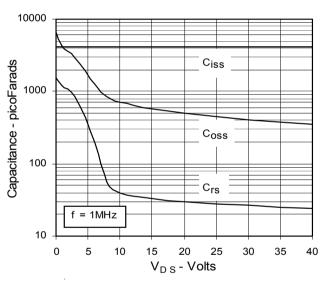


Fig. 12. Forward-Bias Safe Operating Area

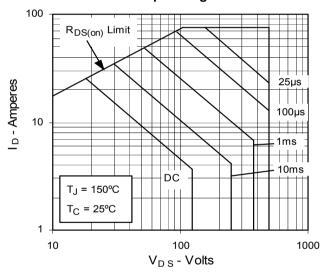
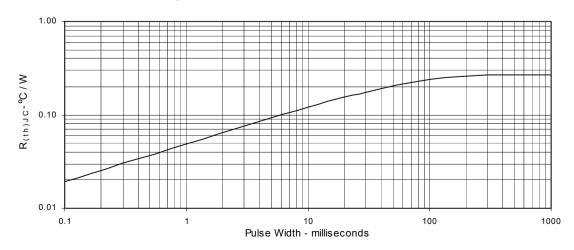
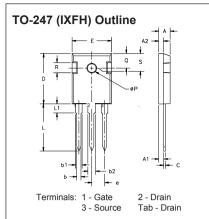


Fig. 13. Maximum Transient Thermal Resistance





Package Outline Drawings



Dim.	Millimeter		Inc	hes
	Min.	Max.	Min. Max	
Α	4.7	5.3	.185	.209
A ₁	2.2	2.54	.087	.102
A ₂	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b₁	1.65	2.13	.065	.084
b ₂	2.87	3.12	.113	.123
С	.4	.8	.016	.031
D	20.80	21.46	.819	.845
Е	15.75	16.26	.610	.640
е	5.20	5.72	0.205	0.225
L	19.81	20.32	.780	.800
L1		4.50		.177
ØP	3.55	3.65	.140	.144
Q	5.89	6.40	0.232	0.252
R	4.32	5.49	.170	.216
S	6.15	BSC	242	BSC

